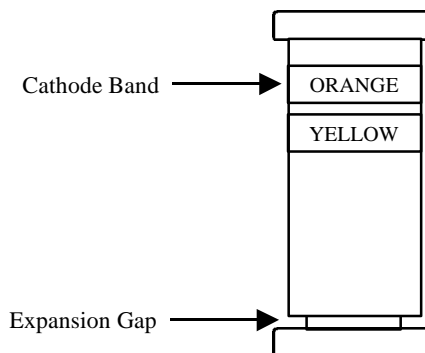


General Description:

A General Purpose diode that couples high forward conductance fast switching speed and high blocking voltages in a glass leadless LL-34 Surface Mount package.

Placement of the Expansion Gap has no relationship to the location of the Cathode Terminal which is indicated by the first color band.



High Conductance, Low Leakage Diode

Absolute Maximum Ratings* $T_A = 25^\circ\text{C}$ unless otherwise noted

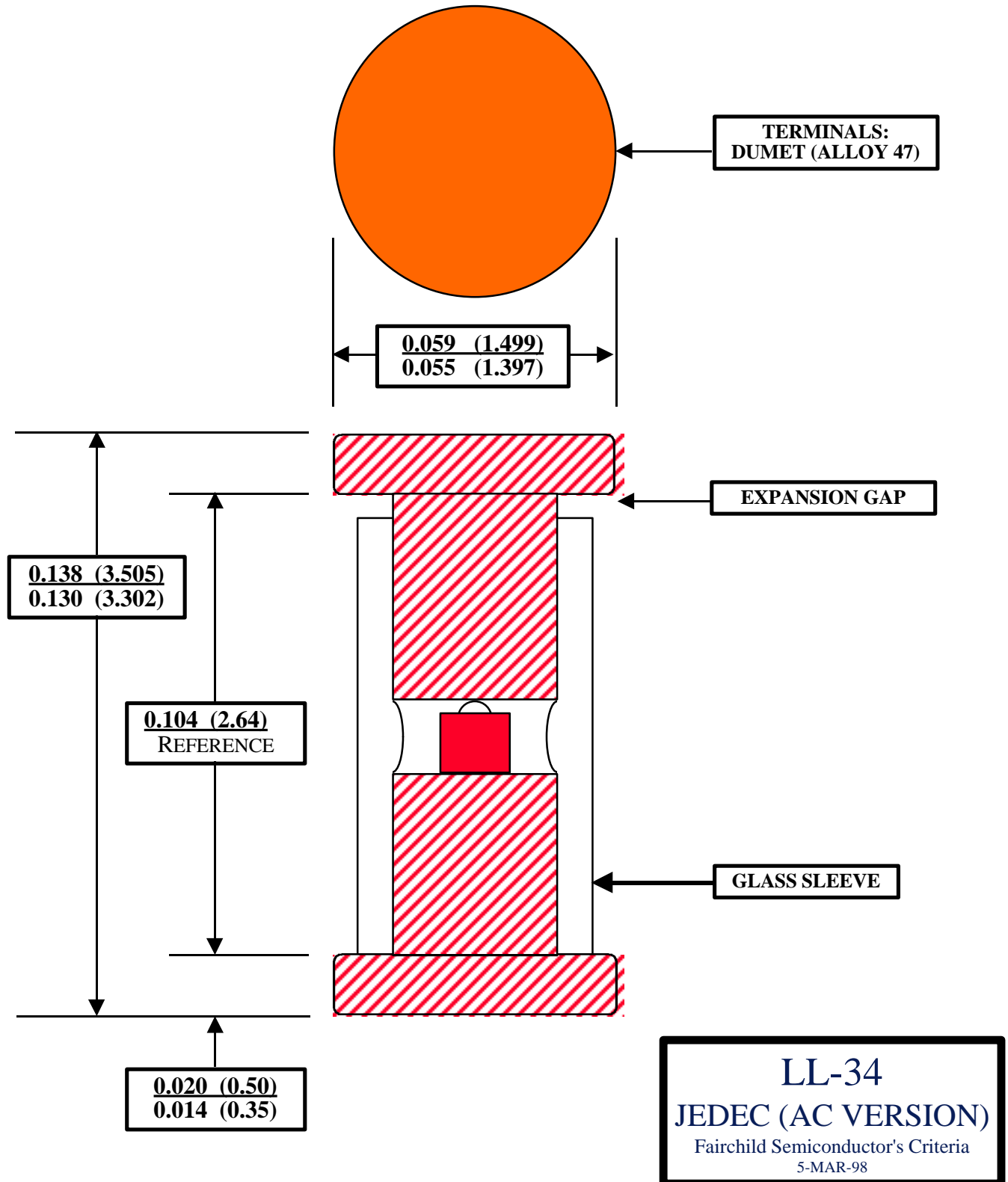
Sym	Parameter	Value	Units
T_{stg}	Storage Temperature	-65 to +200	$^\circ\text{C}$
T_J	Operating Junction Temperature	-65 to +200	$^\circ\text{C}$
P_D	Total Power Dissipation at $T_A = 25^\circ\text{C}$	500	mW
	Linear Derating Factor from $T_A = 25^\circ\text{C}$	3.33	mW/ $^\circ\text{C}$
R_{OJA}	Thermal Resistance Junction-to-Ambient	350	$^\circ\text{C}/\text{W}$
W_{iv}	Working Inverse Voltage	125	V
I_O	Average Rectified Current	200	mA
I_F	DC Forward Current (IF)	500	mA
i_f	Recurrent Peak Forward Current	600	mA
$i_{F(surge)}$	Peak Forward Surge Current (IFSM) Pulse Width = 1.0 second	1.0	Amp
	Pulse Width = 1.0 microsecond	4.0	Amp

*These ratings are limiting values above which the serviceability of any semiconductor device may be impaired

Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

SYM	CHARACTERISTICS	MIN	MAX	UNITS	TEST CONDITIONS
B_V	Breakdown Voltage	150		V	$I_R = 100 \mu\text{A}$
I_R	Reverse Leakage		1.0	nA	$V_R = 125 \text{ V}$
			300	nA	$V_R = 30 \text{ V } T_A = 125^\circ\text{C}$
			500	nA	$V_R = 125 \text{ V } T_A = 125^\circ\text{C}$
			3.0	μA	$V_R = 180 \text{ V } T_A = 150^\circ\text{C}$
V_F	Forward Voltage	520	680	mV	$I_F = 1.0 \text{ mA}$
		600	750	mV	$I_F = 5.0 \text{ mA}$
		650	800	mV	$I_F = 10 \text{ mA}$
		750	880	mV	$I_F = 50 \text{ mA}$
		790	920	mV	$I_F = 100 \text{ mA}$
		0.83	1.00	V	$I_F = 200 \text{ mA}$
C_T	Capacitance		8.0	pF	$V_R = 0.0 \text{ V}, f = 1.0 \text{ MHz}$
T_{RR}	Reverse Recovery Time		3.0	us	$I_F = 10 \text{ mA } V_R = 3.5 \text{ V}$ $R_L = 1.0 \text{ k}\Omega$

THE PLACEMENT OF THE EXPANSION GAP HAS NO RELATIONSHIP TO THE LOCATION OF THE CATHODE TERMINAL OF THE DEVICE. THE EXPANSION GAP & CATHODE BAND CAN BE ON THE SAME TERMINAL OR AT OPPOSITE TERMINALS OF THE DIODE.



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PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
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